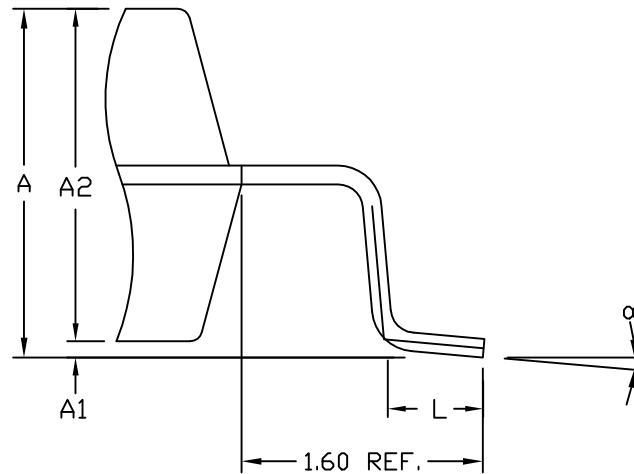
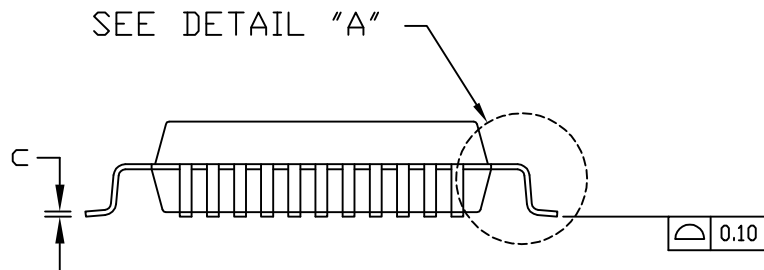


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	--	2.45	--	0.096
A1	0.000	0.250	0.000	0.010
A2	1.800	2.200	0.071	0.087
b	0.290	0.450	0.011	0.018
c	0.110	0.230	0.004	0.009
D	12.954	13.462	0.510	0.530
D1	9.906	10.109	0.390	0.398
D3	8.000	REF	0.315	REF
E	12.954	13.462	0.510	0.530
E1	9.906	10.109	0.390	0.398
E3	8.000	REF	0.315	REF
e	0.800	REF	0.031	REF
L	0.730	1.030	0.029	0.041
α	$^{\circ}0$	$^{\circ}7$	$^{\circ}0$	$^{\circ}7$



DETAIL "A"

NOTES:

1. D1&E1 DO NOT INCLUDE MOLD FLASH.
2. MOLD FLASH OR PROTRUSIONS NOT TO EXCEED 0.25mm(.010").
3. CONTROLLING DIMENSION: MILLIMETER.
4. MEETS JEDEC MS-022-AB.

DALLAS SEMICONDUCTOR **MAXIM**

PROPRIETARY INFORMATION

TITLE: PACKAGE OUTLINE
44L MQFP, 1.60 LEAD FORM

APPROVAL	DOCUMENT CONTROL NO. 21-0826	REV. D	1/1
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